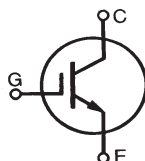
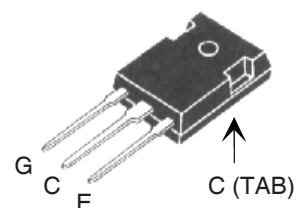


GenX3™ 600V IGBT
IXGH90N60B3
Medium speed low V_{sat} PT IGBTs 5-40 kHz switching


V_{CES}	= 600V
I_{C110}	= 90A
V_{CE(sat)}	≤ 1.8V
t_{fi(typ)}	= 148ns

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T _J = 25°C to 150°C	600	V
V_{CGR}	T _J = 25°C to 150°C, R _{GE} = 1MΩ	600	V
V_{GES}	Continuous	±20	V
V_{GEM}	Transient	±30	V
I_{C25}	T _C = 25°C (Limited by leads)	75	A
I_{C110}	T _C = 110°C (Chip capability)	90	A
I_{CM}	T _C = 25°C, 1ms	500	A
SSOA	V _{GE} = 15V, T _{VJ} = 125°C, R _G = 2Ω	I _{CM} = 180	A
(RBSOA)	Clamped inductive load @ V _{CE} ≤ 600V		
P_C	T _C = 25°C	660	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
M_d	Mounting torque	1.13 / 10	Nm/lb.in.
T_L	Maximum lead temperature for soldering	300	°C
T_{SOLD}	1.6mm (0.062 in.) from case for 10s	260	°C
Weight		6	g

TO-247 AD (IXGH)


G = Gate C = Collector
E = Emitter TAB = Collector

Features

- Optimized for low conduction and switching losses
- Square RBSOA
- International standard package

Advantages

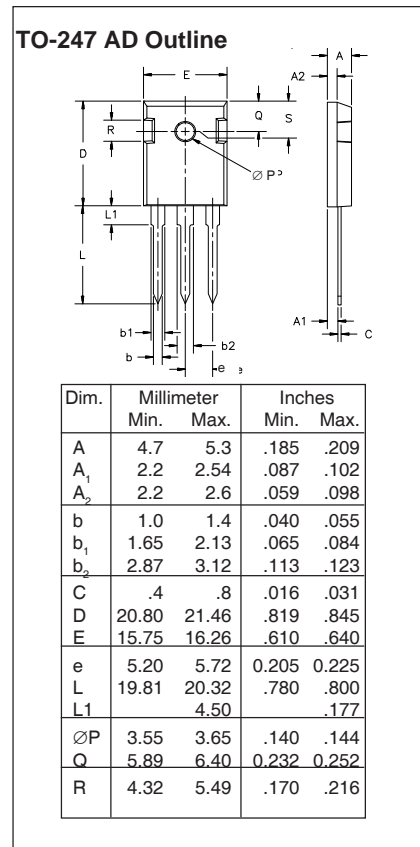
- High power density
- Low gate drive requirement

Applications

- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

Symbol	Test Conditions	Characteristic Values		
		Min.	Typ.	Max.
BV_{CES}	I _C = 250μA, V _{GE} = 0V	600		V
V_{GE(th)}	I _C = 250μA, V _{CE} = V _{GE}	3.0		5.0 V
I_{CES}	V _{CE} = V _{CES} V _{GE} = 0V			75 μA 750 μA
I_{GES}	V _{CE} = 0V, V _{GE} = ±20V			±100 nA
V_{CE(sat)}	I _C = 90A, V _{GE} = 15V, Note 1		1.55 1.62	V V

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	$I_C = 60\text{A}, V_{CE} = 10\text{V}$, Note 1	55	90	S
C_{ies} C_{oes} C_{res}	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$		8285	pF
			525	pF
			140	pF
Q_g Q_{ge} Q_{gc}	$I_C = 90\text{A}, V_{GE} = 15\text{V}, V_{CE} = 0.5 \cdot V_{CES}$		172	nC
			28	nC
			63	nC
$t_{d(on)}$ t_{ri} E_{on} $t_{d(off)}$ t_{fi} E_{off}	Inductive load, $T_J = 25^\circ\text{C}$ $I_C = 60\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 480\text{V}, R_G = 2\Omega$		31	ns
			47	ns
			1.32	mJ
			150	ns
			148	250 ns
			1.37	2.40 mJ
$t_{d(on)}$ t_{ri} E_{on} $t_{d(off)}$ t_{fi} E_{off}	Inductive load, $T_J = 125^\circ\text{C}$ $I_C = 60\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 480\text{V}, R_G = 2\Omega$		29	ns
			43	ns
			1.93	mJ
			220	ns
			253	ns
			2.80	mJ
R_{thJC} R_{thCS}		0.21	0.19 $^\circ\text{C}/\text{W}$ $^\circ\text{C}/\text{W}$	



Note 1: Pulse test, $t \leq 300\mu\text{s}$; duty cycle, $d \leq 2\%$.

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
4,850,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

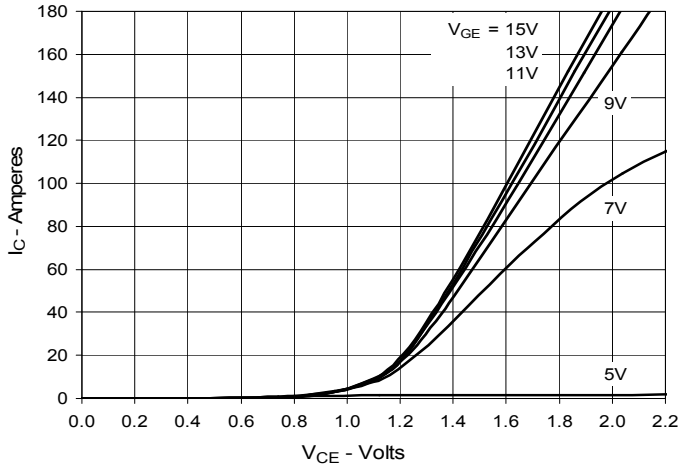
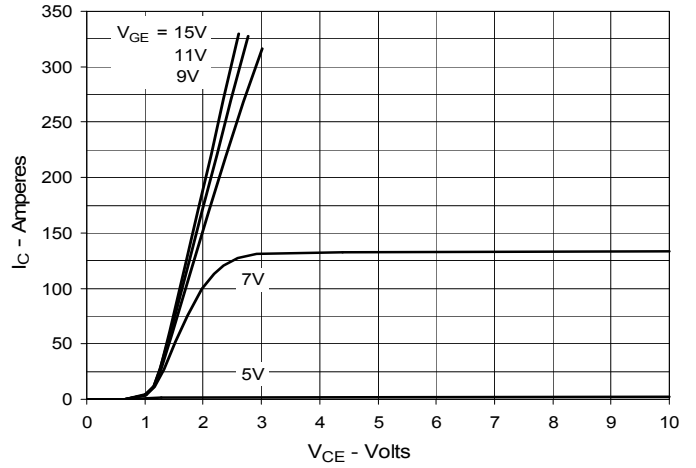
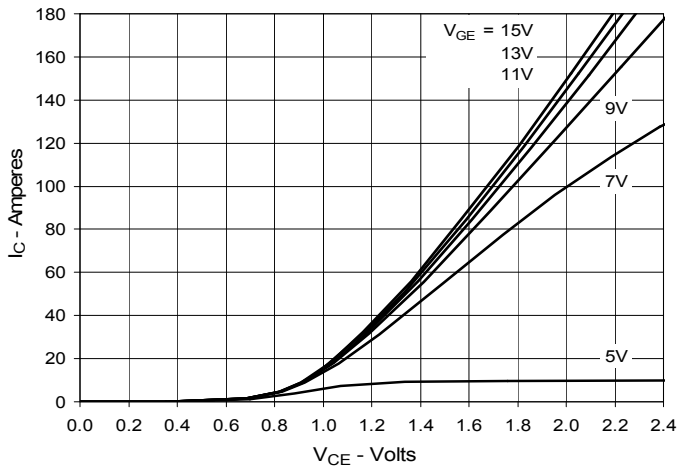
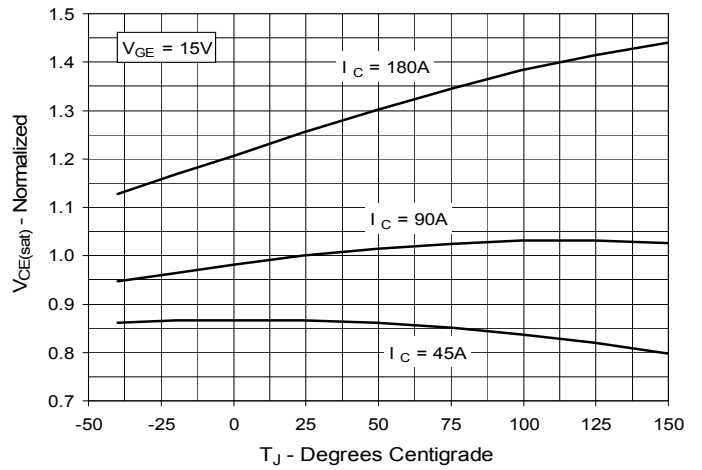
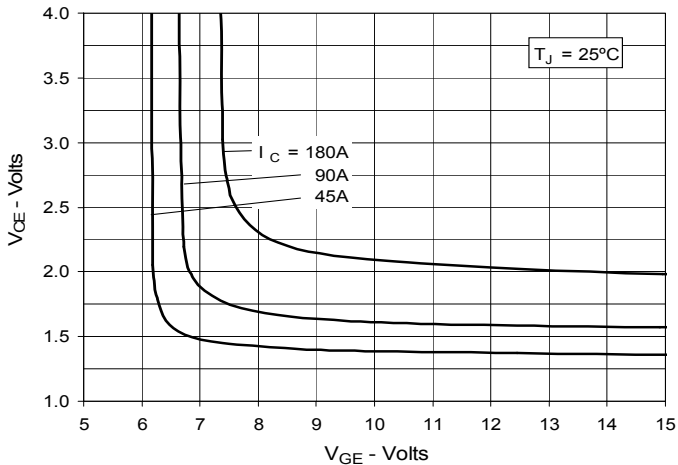
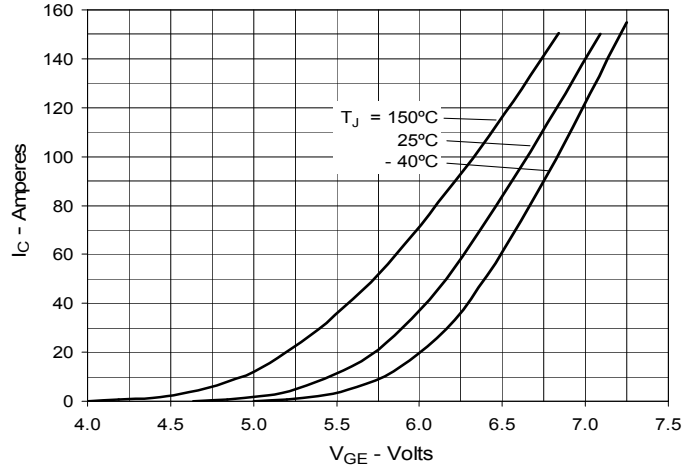
**Fig. 1. Output Characteristics
@ 25°C**

**Fig. 2. Extended Output Characteristics
@ 25°C**

**Fig. 3. Output Characteristics
@ 125°C**

**Fig. 4. Dependence of $V_{CE(sat)}$ on
Junction Temperature**

**Fig. 5. Collector-to-Emitter Voltage
vs. Gate-to-Emitter Voltage**

Fig. 6. Input Admittance


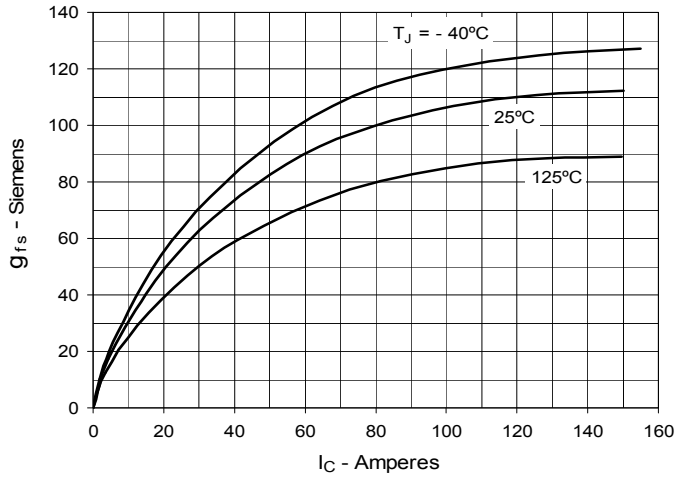
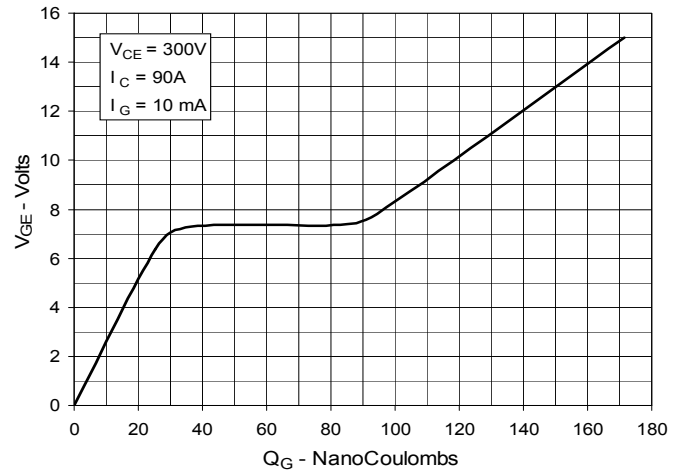
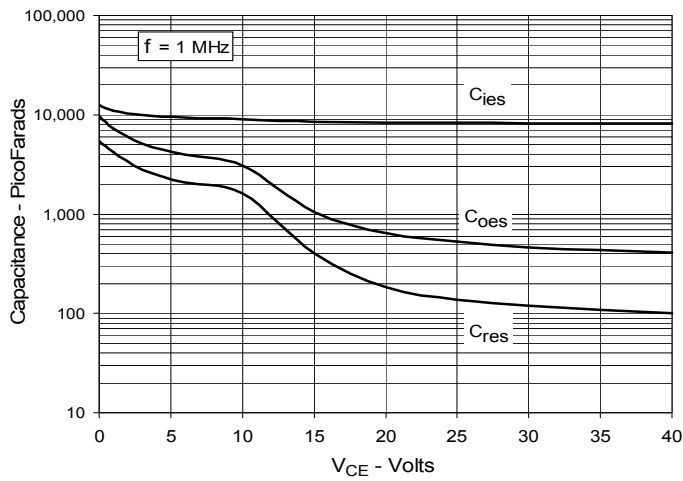
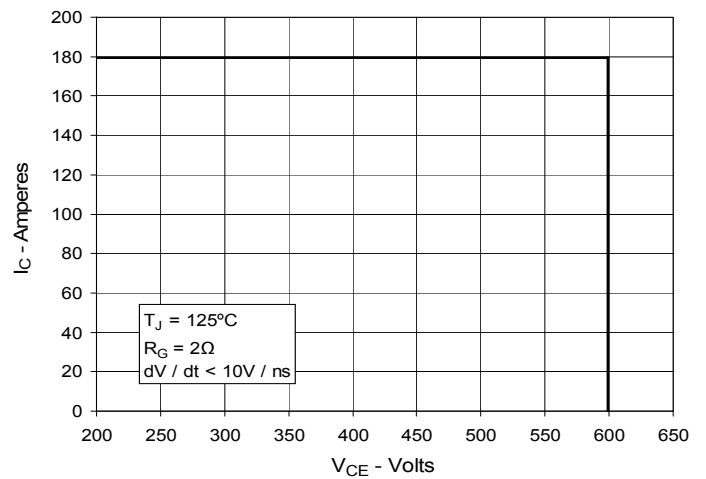
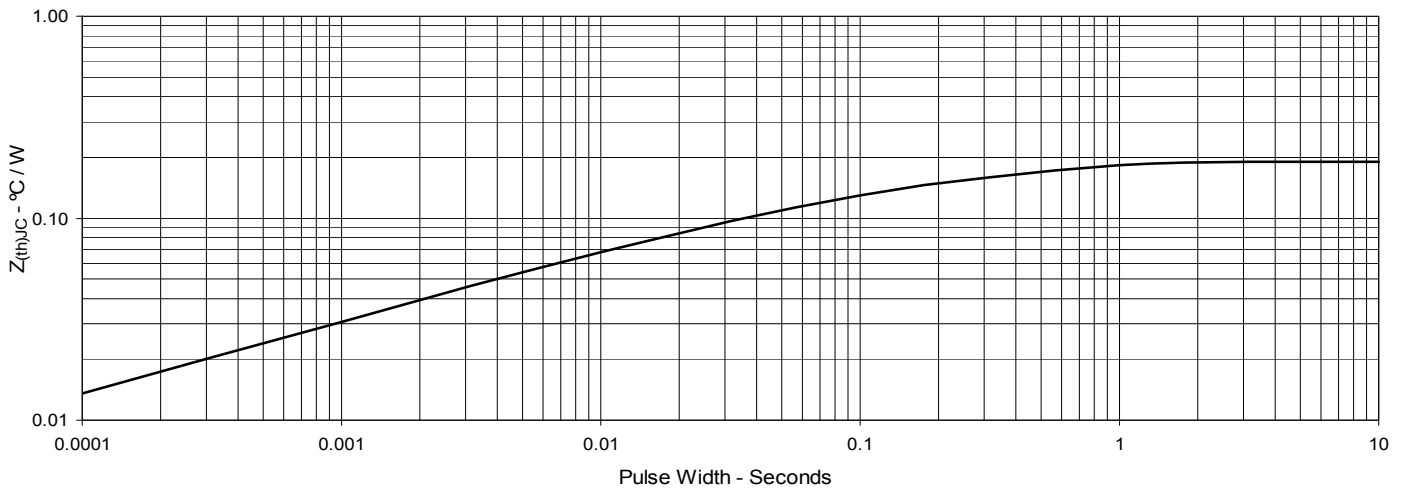
Fig. 7. Transconductance

Fig. 8. Gate Charge

Fig. 9. Capacitance

Fig. 10. Reverse-Bias Safe Operating Area

Fig. 11. Maximum Transient Thermal Impedance


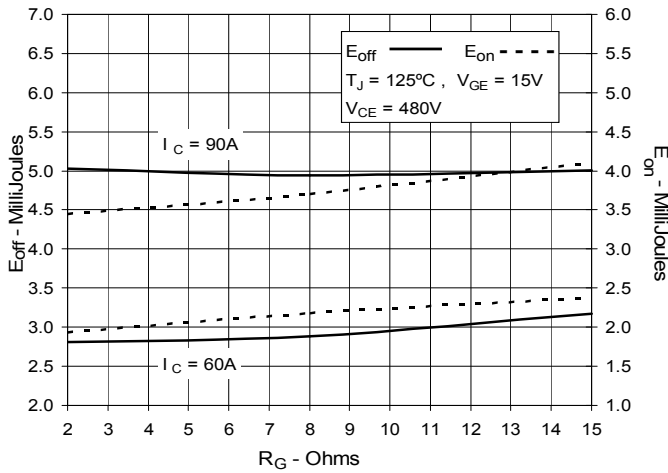
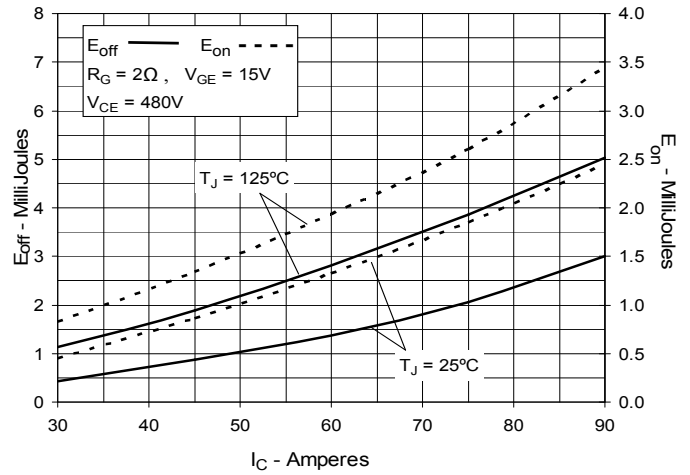
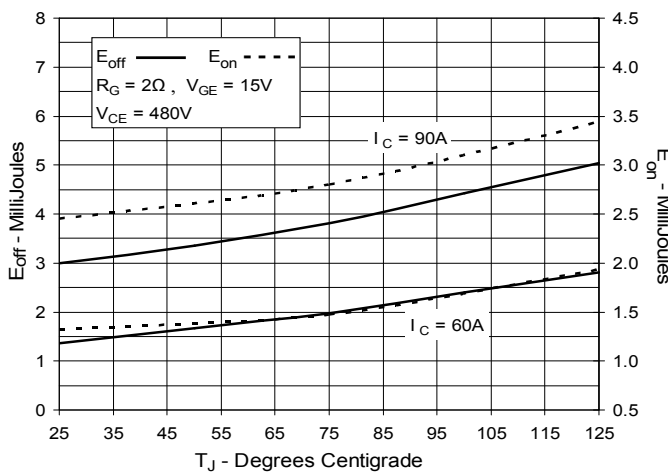
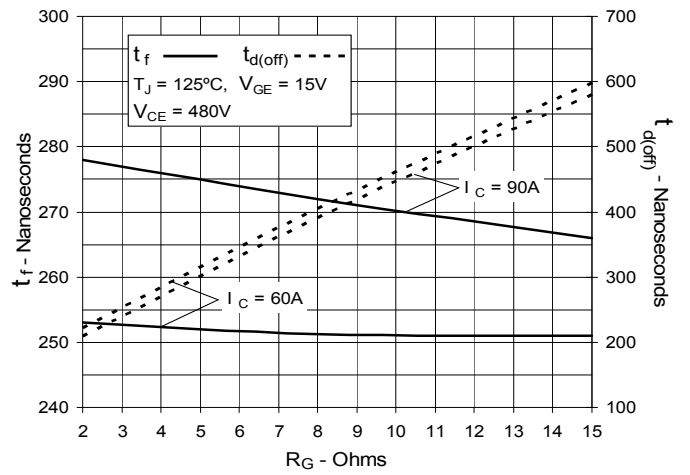
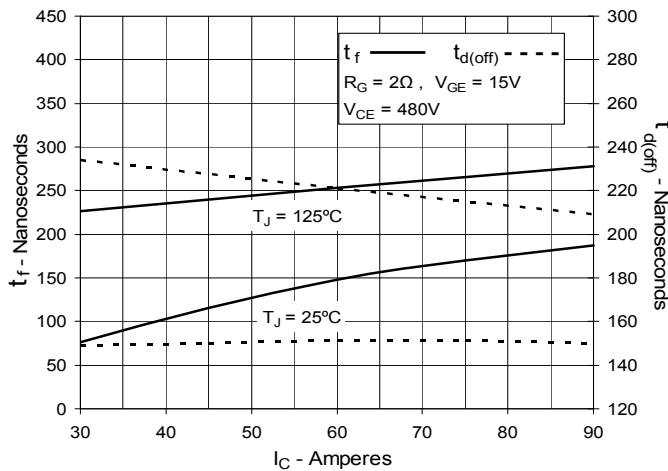
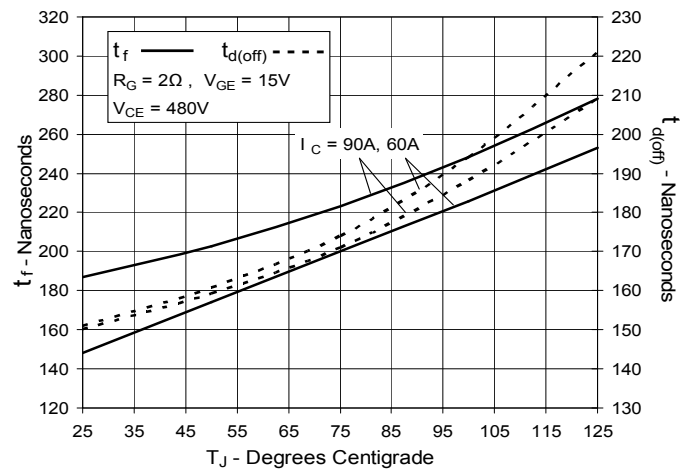
Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance

Fig. 13. Inductive Switching Energy Loss vs. Collector Current

Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature

Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance

Fig. 16. Inductive Turn-off Switching Times vs. Collector Current

Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature


Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance

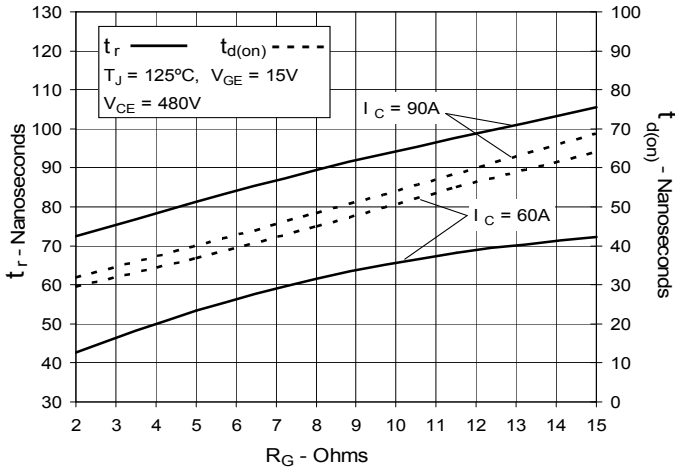


Fig. 19. Inductive Turn-on Switching Times vs. Collector Current

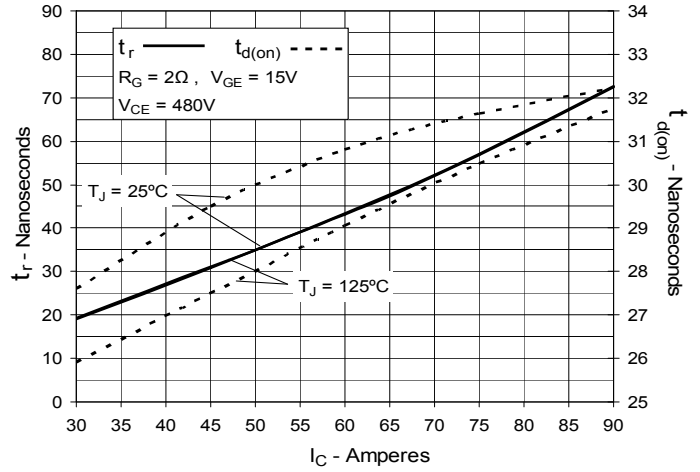


Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature

